

Title (en)
SEMICONDUCTOR SIDE EMITTING LASER LEADFRAME PACKAGE AND METHOD OF PRODUCING SAME

Title (de)
LEITERRAHMENGEGÄUßE FÜR SEITLICH ABSTRAHLENDEN HALBLEITERLASER UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)
BOÎTIER RÉSEAU DE CONDUCTEURS À LASER À ÉMISSION LATÉRALE SEMI-CONDUCTEUR ET SON PROCÉDÉ DE PRODUCTION

Publication
EP 3916933 B1 20230705 (EN)

Application
EP 21174991 A 20210520

Priority
US 202016882858 A 20200526

Abstract (en)
[origin: EP3916933A2] A surface mount laser package for a side-looking semiconductor laser has a substantially planar leadframe with a component side and a board attach side. The component side has a conductive die attach pad and a plurality of wire bond pads. A laser die has an anode surface and a cathode surface, where the cathode surface is mounted to the conductive die attach pad. A plurality of bond wires span between the laser die anode surface and a wire bond pad. A molding encases the laser die and the plurality of bond wires on the component side of the leadframe and also lies between the conductive die attach pad and each of the wire bond pads within a plane of the leadframe. The conductive die attach pad has a metallization layer on the leadframe and each of the bond pads has a metallization layer on the leadframe.

IPC 8 full level
H01S 5/02234 (2021.01); **H01L 21/56** (2006.01); **H01L 23/00** (2006.01); **H01L 23/31** (2006.01); **H01L 23/482** (2006.01); **H01L 23/495** (2006.01); **H01L 33/48** (2010.01); **H01S 5/0232** (2021.01); **H01S 5/026** (2006.01); **H01S 5/40** (2006.01)

CPC (source: CN EP US)
H01L 21/561 (2013.01 - EP); **H01L 23/3107** (2013.01 - EP); **H01L 23/4824** (2013.01 - EP); **H01L 23/49541** (2013.01 - EP); **H01L 23/49582** (2013.01 - EP); **H01L 24/49** (2013.01 - EP); **H01L 24/97** (2013.01 - EP); **H01S 5/02234** (2021.01 - EP US); **H01S 5/0232** (2021.01 - CN EP US); **H01S 5/02345** (2021.01 - CN US); **H01L 24/29** (2013.01 - EP); **H01L 24/32** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 24/83** (2013.01 - EP); **H01L 24/85** (2013.01 - EP); **H01L 24/92** (2013.01 - EP); **H01L 2224/29101** (2013.01 - EP); **H01L 2224/2919** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/48465** (2013.01 - EP); **H01L 2224/49111** (2013.01 - EP); **H01L 2224/49171** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/83001** (2013.01 - EP); **H01L 2224/83801** (2013.01 - EP); **H01L 2224/8385** (2013.01 - EP); **H01L 2224/85001** (2013.01 - EP); **H01L 2224/92247** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP); **H01L 2924/12042** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01S 5/02345** (2021.01 - EP); **H01S 5/026** (2013.01 - EP); **H01S 5/4031** (2013.01 - EP)

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